

# WP5.2a: IP Blocks in 28nm for the HEP Community

Design Team: Franco N. Bandi, Rafael Ballabriga, Davide Ceresa, Simone Emiliani, Tobias Hofmann, Jan Kaplon, Stefano Michelis, Markus Piller, Giacomo Ripamonti, Viros Sriskaran, Gianluca Traversi Test Team: Giulio Borghello, Francisco Piernas Díaz, Risto Pejasinovic ASICs Technologies & Foundry Services: Marco Andorno, Alessandro Caratelli, Kostas Kloukinas

Contact: franco.nahuel.bandi@cern.ch



#### WP5.2a: What we do?



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Intellectual Property (IP) blocks design

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Intellectual Property (IP) blocks use

IP block example: DAC, ADC, voltage reference, transmitter, receiver, PLL... \*thanks to CERN ASIC Support Team: A. Caratelli and M. Andorno



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IP Blocks in 28nm for HEP 3/ 20

#### Documentation

Analog IP Blocks

Conclusions



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### Motivation

- Familiarize new designers with the technology (short document with practical information)<sup>1</sup>.
- We propose guidelines to homogenize choices and enable block sharing within the community.



<sup>1</sup>The documentation is available (thanks to CERN ASIC Support Team: A. Caratelli and M. Andorno):

- Web page: https://asicsupport.web.cern.ch/
- Forum: https://asicsupport-community.web.cern.ch/



## Designer's Guide and Technology Overview

We have prepared a "Designer's Guide" with selected technical information and proposed design guidelines that facilitate collaborative design work. Features of the technology:

- 28nm CMOS process.
- Single poly and 9 metal stack + AP (AL RDL).
- 0.9V core transistors (ulvt, lvt, reg, uhvt and sr) and 1.8 I/O transistors.
- Retrograde twin well and Deep N-well.
- High-R, unsilicided diffusion, N-Well...
- MOMcap and MOScap.
- Only vertical poly is allowed<sup>2</sup>.

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<sup>2</sup>Enclosed layout not possible. Also, some IP blocks need vertical and horizontal version (extra work!!).



#### Datasheets



Transmitter and receiver layout

#### Electromigration analysis



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# IP Block Library (Design Finished)

Circuits to share	Notes
Bandgap voltage reference	Block submitted in January 2022. Develop-
and temperature monitor	ment lead by <b>G. Traversi (Bergamo/Pavia)</b>
	collaboration with the INFN Falaphel project
	with support from CERN engineers.
Digital to Analog	Core block submitted in January 2022.
Converter (8-bit)	Development lead by M. Piller (DOCT,
	Austrian programme).
Differential line drivers	Block submitted in January 2022. Develop-
and receivers	ment lead by F. Bandi (WP5 FELL).
Rail to Rail Operational	Completed. To be submitted in 2022.
Amplifier	Development lead by J. Kaplon (STAFF).
Radiation tolerant ESD	Design outsorced to Sofics.
protections	

Design followed guidelines for radiation hardness from the initial technological characterization. Testing ongoing for validating the design.



### Bandgap Voltage Reference (by G. Traversi)

Designed by Bergamo-Pavia in collaboration with the INFN Falaphel project (Main designer: G. Traversi) and technical support from CERN.

Parameter	Min	Тур	Max	Unit	
Voltage supply	0.81	0.9	0.99	V	
Output voltage		480		mV	
Current supply		100		μA	
Temperature	-40	25	60	°C	
$\Delta$ Vref max vs Temp		3		mV	
$\Delta$ Vref max vs Vdd $\pm 10\%$		2		mV	
Target PSR (low frequencies)		40		dB	
Active element	lvt in weak inversion				



## 8 Bit DAC (by M. Piller)

The 8 bit digital-to-analog converter is intent to be a IP block for biasing purposes.

- 8 bit digital-to-analog conversion.
- Output voltage before RtR 0 to  $V_{DD}/2$ .
- INL < 0.5.
- I<sub>LSB</sub> digital current adjustment.
- $I_{LSB} = 50 nA.$

Parameter	Min	Тур	Max	Unit
Voltage supply	0.81	0.9	0.99	V
INL			0.38	
Temperature	-40	25	80	°C
Area	220×267			μm <sup>2</sup>
Metal stack	1-2-3			metals
		(4,5 power)		







# SLVS Transmitter and Receiver (by F. Bandi)

The design targets mainly on-board chip-to-chip communication in rad-hard applications (1 Grad). Therefore, only thin-gate transistor should be used to ensure higher radiation tolerance [1].

- Disable signal.
- Inverter function.
- Compatible with low voltage design (V\_{ddcore} = 0.8 V).
- Level shifting: from  $V_{ddcore}$  to  $V_{ddIO}$ .
- Tx:  $I_{out} = 4 \text{ mA}$ .
- Rx: termination on/off switch and fail-safe resistors.

Parameter	Min	Тур	Max	Unit
IO voltage supply	1.08	1.2	1.32	V
Core voltage supply	0.72	0.9	0.99	V
Data rate	0		1.28	Gbps
Temperature	-40		80	°C
Area with ESD		180×80		μm <sup>2</sup>
Metal stack		1-2-3(4 power)		metals







# Rail to Rail OPAMP (by J. Kaplon)

Parameter	Min	Тур	Max	Unit
Open loop Gain	70	75		dB
GBP (uncompensated)		1.6		GHz
Current supply			400	μA
PM (unity gain for 0-1nF	66	74		0
load and $10\Omega$ series				
resistor required)				
Settling time (1%)			35	ns
Output noise (unity gain)			150	μV
Offset rms (unity gain)			1.5	mV
Area (amplifier and bias)	44 ×	70 + 44	$1 \times 90$	μm <sup>2</sup>
Area (amplifier, bias,	1	40  imes 16	50	μm <sup>2</sup>
decoupling and compensation)				



#### Characterization Set-up



Figure: Left, PCB with wire-bonded chip (bottom) and common test system (top). Right, eye diagram at 640 MHz (preliminary). Acknowledgment: Giulio Borghello, Davide Ceresa, Francisco Piernas Díaz, Risto Pejasinovic.



## IP Block Library (Work In Progress)

Circuits to share	Notes
Analog to Digital Converter	In progress. Development lead by
for monitoring (12-bit)	T. Hofmann (WP5 FELL). Synergies WP6.
Rail to Rail Operational	In progress. To be submitted in 2022.
Amplifier (slow (e.g. monitoring	Development lead by M. Piller
in unity gain configuration))	(DOCT, Austrian programme).
Analog PLL	In progress. Development lead by F. Bandi.
	Synergies with LHCb PicoPix project.
Digital PLL	Design start expected for Q4 2022. Develop-
	ment lead by T. Hofmann (WP5 FELL).
DCDC converter and LDO	In progress. Development lead by S. Michelis
	(STAFF) and G. Ripamonti (STAFF)
Radiation tolerant CMOS IO Pad	Design outsorced to Sofics

Application specific blocks (front-end): amplification, filtering and discrimination:

- For 2-D readout circuits (input cap. <100fF and leakage current per pixel <20nA). Collaboration WP1.1-WP5 (V. Sriskaran (WP1.1 FELL) and S. Emiliani (WP5 TECH)).
- For sensors with intrinsic amplification (SiPM, MCP, PMT). M. Piller (DOCT, Austrian Programme).



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#### Conclusions

- We have created documentation for quick adoption of the technology for the community (technology overview, designer's guide...).
- Some IP blocks were submitted in January 2022 and more circuits are under design. The blocks are documented.
- We have created synergies with other WPs and with external groups in the community:
  - WP1.1: Charge sensitive amplifier, shaper and comparator for 2-D readout circuits. V. Sriskaran (FELL WP1.1) and S. Emiliani (TECH WP5).
  - WP6: 12-bit Analog to Digital Converter for monitoring. T. Hofmann (FELL WP5).
  - Bandgap codesign by G. Traversi at University of Bergamo/Pavia in collaboration with the INFN Falaphel project.



#### Future Work

- The characterization of prototypied blocks has started (functional). TID measurements will start in the following weeks (see Davide's presentation).
- A design programme has been determined for the coming years (APLL, DPLL, high resolution ADC).
- However, the results from testing will determine the future efforts:
  - Iterate on some of the blocks to make them more rad hard.
  - Focus the design effort on new IP blocks (for example in case of SRAMs not being radiation-hard enough).



# Bibliography

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